



Material Content Data Sheet



Halogen-Free

Sales Product Name	IRF200P223	Issued	21. July 2021
MA#	MA005540057		
Package	PG-TO247-3-901	Weight*	5737.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	0.31	0.31	3061	3061
leadframe	inorganic material	phosphorus	7723-14-0	1.131	0.02		197	
	non noble metal	iron	7439-89-6	3.771	0.07		657	
	non noble metal	copper	7440-50-8	3,765.728	65.64	65.73	656370	657224
wire	non noble metal	aluminium	7429-90-5	17.179	0.30	0.30	2994	2994
encapsulation	organic material	carbon black	1333-86-4	9.538	0.17		1662	
	plastics	epoxy resin	-	381.517	6.65		66499	
	inorganic material	silicondioxide	60676-86-0	1,516.529	26.43	33.25	264333	332494
leadfinish	non noble metal	tin	7440-31-5	13.948	0.24	0.24	2431	2431
solder	non noble metal	tin	7440-31-5	0.206			36	
	noble metal	silver	7440-22-4	0.258			45	
	non noble metal	lead	7439-92-1	9.839	0.17	0.17	1715	1796
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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